

IN THE SPECIFICATION

Please replace paragraph [0035] with the following amended paragraph:

[0035] The use of heat tunnel 240 minimizes thermal dissipation of the heated embossable film of the disk substrate. Thermal dissipation may lead to inconsistencies in the embossable film and subsequent inconsistencies in the embossed pattern. As discussed above, heat tunnel 240 maintains the approximate embossing temperature of the heated embossable film until the disk substrate is placed in the die assembly. Although the embossing foils in die assembly 210 may be heated, a heated embossable film may result in a quicker and more efficient imprint. Moreover, by positioning heater assembly 280 relatively close to die assembly 210, thermal distortion of the embossable film is minimized.

IN THE DRAWINGS

The attached sheets include changes to FIGS. 2, 4, 4A, 5A, 5B, 15A, and 15B. These sheets replace the originally filed sheets that included FIGS. 2, 4, 4A, 5A, 5B, 15A, and 15B. These figures have been amended to correct typographical errors. It is respectfully submitted that the proposed amendments to the drawings do not add new matter. In particular, support for the amendments to FIG. 2 may be found on page 8, paragraph [0033]. Support for the amendments to FIG. 4 may be found on page 12, paragraph [0038]. Support for the amendment to FIG. 4A may be found on page 12, paragraphs [0038] and [0039]. Support for the amendments to FIGS. 5A and 5B may be found on page 16, paragraph [0044]. Support for the amendments to FIGS. 15A and 15B may be found on page 28, paragraphs [0063] and [0068].

Attachment: Replacement Sheets
Annotated Sheets Showing Changes